



ACM Research Enters Dry Processing Market with Launch of Ultra Furnace

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- *ACM's First Furnace Product Targets LPCVD Initially, Oxidation , Annealing and ALD in Future*
- *Demonstrates Effectiveness of Korea and China R&D Team Collaboration*

FREMONT, Calif., April 28, 2020 (GLOBE NEWSWIRE) -- ACM Research, Inc. ("ACM" or the "Company") (NASDAQ:ACMR), a leading supplier of wafer cleaning technologies for advanced semiconductor devices, today unveiled the Ultra Furnace, its first system developed for multiple dry processing applications. Initially optimized to deliver high performance for low-pressure chemical vapor deposition (LPCVD), the Ultra Furnace also leverages the same platform to be used for oxidation and annealing processes, as well as for atomic layer deposition (ALD). This achievement represents a two-year collaboration between ACM's R&D teams located in China and Korea.

"Advanced technology nodes present ongoing challenges that require innovation from the capital equipment suppliers. This demanding environment provides significant opportunities for ACM," explained Dr. David Wang, CEO of ACM Research. "Continuous innovation is in our DNA. We saw a market need that could benefit from our technology, and expanded our reach into a new market segment. The addition of the Ultra Furnace to ACM's established portfolio of wet processing tools, expands our opportunity by providing an integrated solution to our customers' advanced products."

"The Ultra Furnace product is the result of collaboration between our talented experts in China and Korea to develop differentiated technology," stated YY Kim, CEO of ACM Research Korea. "ACM's team in Korea was established to complement the talents of our world-class Shanghai team, accelerate our time to market, and provide outstanding technical support to our local customers."

Deposition processes utilize process gases at a high temperature to react with each other on a silicon wafer, forming a silicon oxide or nitride layer on the wafers. The Ultra Furnace system is intended for batch processing of up to 100 12-inch (300mm) wafers. The innovative system design combines newly developed hardware that improves durability, with the company's proven software technology and a proprietary control system and algorithm. This enables the tool to provide stable control of pressure, gas flow rate and temperature.

While the Ultra Furnace system targets LPCVD processes, with a few changes to the components and layout, each tool can address other target applications. About 85 percent of the hardware configuration remains unchanged, so the alterations for the new application can be achieved efficiently.

ACM Research intends to target customers in China initially, before expanding the offering of the Ultra Furnace into Korea and Taiwan later. ACM delivered the first Ultra Furnace tool to a key logic customer's manufacturing facility in China in early 2020. This tool targets LPCVD, and has been installed in a production environment to begin qualification.

To learn more about the Ultra Furnace, please call the ACM contact for your region listed below.

About ACM Research, Inc.

ACM develops, manufactures and sells semiconductor process equipment for single wafer or batch wet cleaning, Electroplating, Stress free polishing and thermal process are critical to advanced semiconductor device manufacturing, as well as wafer-level packaging. The company is committed to delivering customized, high performance, cost-effective process solutions that semiconductor manufacturers can use in numerous manufacturing steps to improve productivity and product yield.

Forward-Looking Statements

Statements contained in the second paragraph of this press release are not historical facts and may be forward-looking statements within the meaning of the Private Securities Litigation Reform Act of 1995. Forward-looking statements include statements regarding the intent, belief or current expectations with respect to the potential success of the offering and sale of the Ultra Furnace system. Such statements, which are expectations only, reflect management's current views, are based on certain assumptions, and involve risks and uncertainties. Actual results, events, or performance may differ materially from the above forward-looking statements due to a number of important factors, and will be dependent upon a variety of factors, including, but not limited to, introduction of competing products by other companies, lack of market acceptance of the Ultra Furnace, and economic concerns, including the unpredictability of current markets resulting from the ongoing COVID-19 pandemic. ACM Research undertakes no obligation to publicly update these forward-looking statements to reflect events or circumstances that occur after the date hereof or to reflect any change in its expectations with regard to these forward-looking statements or the occurrence of unanticipated events.

Media Contact:

Eric Lawson

Kiterocket

+1 480.276.9572

elawson@kiterocket.com

Company Contact:

USA

Sallyann Henry

ACM Research, Inc.

+1 510.445.3700

China

Xi Wang

ACM Research (Shanghai), Inc.

+86 21 50808868

Korea

YY Kim

ACM Research (Korea), Inc.

+821041415171

Taiwan

Arthur Hsu

+886 910663885

Singapore

Adrian Ong

+65 8813-1107



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